ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® MALECTRONICS INDUSTRIES®	PC. Bannockl	burn. Illinois. A	Il rights reserved untions.	under both	This docum level parts, t	ent is a declara	tion of the encompass	substances es all lowe	within the er level ma	e manufacture terials for wh	er listed it hich the m	em. Note: anufactur	: if the item is an a er has engineering	ssembly with lowe responsibility.
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier Information														
Company name* Co			Company unique ID			Unique ID Authority					Response Date*			
onsemi							,				2025-05-10			
Contact Name Title - Contact			ct	Pł			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title -			tle - Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number		umber Mfr Item Name			Effective Da	Effective Date Version Manufacturing Si		ring Site	1	Weight*	UOM	Unit Type	
	NCP347	NCP347MTAFTBG OVE		OVER VOLTAGE PROTECTION		2025-05-10			MY1		1	2.23	mg	Each
Manufacturing Proccess Informa	tion						-							
Terminal Plating / Grid Array Ma	rid Array Material Terminal Base All		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		re Max T	Max Time at Peak Tempera		ure Nun	nber of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30		secon	ds <b>3</b>		
Comments														
evel 1 - maximum time at peak temperatu	ire during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth							
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).										
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure		
Die	0.65	mg	Supplier	Silicon (Si)	7440-21-3		0.65	mg		
Die Attach	0.29	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.2436	mg		
			Supplier	Silver (Ag)	7440-22-4		0.0464	mg		
Lead Frame	4.12	mg	Supplier	Silver (Ag)	7440-22-4		0.0824	mg		
			Supplier	Zinc (Zn)	7440-66-6		0.0041	mg		
			Supplier	Iron (Fe)	7439-89-6		0.0906	mg		
			Supplier	Copper (Cu)	7440-50-8		3.9428	mg		
Mold Compound-Black	6.41	mg		Epoxy Phenol Resin	proprietary data		0.5769	mg		
			Supplier	Fused Silica (SiO2)	60676-86-0		5.8331	mg		
Plating	0.63	mg	Supplier	Tin (Sn)	7440-31-5		0.63	mg		
Wire Bond - Au	0.13	mg	Supplier	Gold (Au)	7440-57-5		0.13	mg		